

Most Frequently Occurring Classifications of Patents Returned
From A Search of 10/600,799 on November 05, 2004

Combined Classifications

9 257/713	3 438/106
9 257/E23.087	3 438/108
8 257/E23.09	2 29/841
7 257/704	2 174/52.2
7 361/719	2 257/685
6 257/706	2 257/686
6 257/722	2 257/698
6 257/E21.511	2 257/703
6 257/E23.125	2 257/708
6 257/E23.189	2 257/717
6 257/E25.012	2 257/724
6 361/705	2 257/759
5 29/832	2 257/786
5 165/185	2 257/E23.069
5 165/80.2	2 257/E23.079
5 174/16.3	2 257/E23.084
5 257/697	2 257/E23.094
5 257/778	2 257/E23.098
5 257/E23.102	2 257/E23.101
5 257/E23.104	2 257/E23.105
5 257/E23.181	2 257/E23.106
4 29/840	2 257/E23.107
4 165/80.3	2 257/E23.126
4 257/707	2 257/E23.19
4 257/720	2 257/E23.193
4 257/738	2 257/E25.013
4 361/704	2 264/272.17
4 361/715	2 361/690
3 257/690	2 361/714
3 257/712	2 361/735
3 257/714	2 361/784
3 257/718	2 438/107
3 257/723	2 438/122
3 257/737	2 438/126
3 257/E21.503	
3 257/E23.067	
3 257/E23.092	
3 257/E23.119	
3 361/717	
3 361/718	
3 361/783	

9 257/713 (2 OR, 7 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

- 257/688 .With large area flexible electrodes in press contact with opposite sides of active semiconductor chip and surrounded by an insulating element, e.g., ring
- 257/712 .With provision for cooling the housing or its contents
- 257/713 ..For integrated circuit

9 257/E23.087 (0 OR, 9 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

- 257/E23.079 ..For integrated circuit devices, e.g., power bus, number of leads (EPO)
- 257/E23.08 .Arrangements for cooling, heating, ventilating or temperature compensation; temperature-sensing arrangements (EPO)
- 257/E23.087 ..Fillings or auxiliary members in containers or encapsulations selected or arranged to facilitate heating or cooling (EPO)

8 257/E23.09 (0 OR, 8 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

- 257/E23.079 ..For integrated circuit devices, e.g., power bus, number of leads (EPO)
- 257/E23.08 .Arrangements for cooling, heating, ventilating or temperature compensation; temperature-sensing arrangements (EPO)
- 257/E23.087 ..Fillings or auxiliary members in containers or encapsulations selected or arranged to facilitate heating or cooling (EPO)
- 257/E23.09 ...Auxiliary members in containers characterized by their shape, e.g., pistons (EPO)

7 257/704 (2 OR, 5 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

- 257/688 .With large area flexible electrodes in press contact with opposite sides of active semiconductor chip and surrounded by an insulating element, e.g., ring
- 257/701 .Insulating material
- 257/704 ..Cap or lid

7 361/719 (1 OR, 6 XR)

Class 361 : ELECTRICITY: ELECTRICAL SYSTEMS AND DEVICES

- 361/600 HOUSING OR MOUNTING ASSEMBLIES WITH DIVERSE ELECTRICAL COMPONENTS
- 361/679 .For electronic systems and devices
- 361/688 ..With cooling means
- 361/704 ...Thermal conduction
- 361/717For active solid state devices
- 361/718For integrated circuit
- 361/719Circuit board mounted

6 257/706 (1 OR, 5 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

- 257/688 .With large area flexible electrodes in press

contact with opposite sides of active semiconductor chip
and surrounded by an insulating element, e.g., ring
257/701 .Insulating material
257/706 ..With heat sink

6 257/722 (1 OR, 5 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/688 .With large area flexible electrodes in press
contact with opposite sides of active semiconductor chip
and surrounded by an insulating element, e.g., ring
257/712 ..With provision for cooling the housing or its
contents
257/721 ..With gas coolant
257/722 ...With fins

6 257/E21.511 (0 OR, 6 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E21.001 PROCESSES OR APPARATUS ADAPTED FOR MANUFACTURE
OR TREATMENT OF SEMICONDUCTOR OR SOLID-STATE DEVICES OR

OF

PARTS THEREOF (EPO)

257/E21.002 .Manufacture or treatment of semiconductor
device (EPO)
257/E21.04 ..Device having at least one potential-jump
barrier or surface barrier, e.g., PN junction, depletion
layer, carrier concentration layer (EPO)
257/E21.499 ...Assembling semiconductor devices, e.g.,
packaging, including mounting, encapsulating, or treatment
of packaged semiconductor (EPO)
257/E21.506 Attaching or detaching leads or other
conductive members, to be used for carrying current to or
from device in operation (EPO)
257/E21.509 Involving soldering or alloying process,
e.g., soldering wires (EPO)
257/E21.511 Mounting on insulating member provided
with metallic leads, e.g., flip-chip mounting, conductive
die mounting (EPO)

6 257/E23.125 (0 OR, 6 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E23.113 Ceramic materials or glass (EPO)
257/E23.116 ..Encapsulations, e.g., encapsulating layers,
coatings, e.g., for protection (EPO)
257/E23.123 ..Characterized by arrangement or shape (EPO)

257/E23.124 ...Device being completely enclosed (EPO)
257/E23.125 Substrate forming part of encapsulation
(EPO)

6 257/E23.189 (0 OR, 6 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E23.176 ...For flat cards, e.g., credit cards (EPO)
257/E23.18 ..Containers; seals (EPO)
257/E23.181 ..Characterized by shape of container or parts,
e.g., caps, walls (EPO)
257/E23.188 ...Container being hollow construction and

having insulating or insulated base as mounting for
semiconductor body (EPO)
257/E23.189Leads being parallel to base (EPO)

6 257/E25.012 (0 OR, 6 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E25.001 ASSEMBLIES CONSISTING OF PLURALITY OF
INDIVIDUAL SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES

(EPO)

257/E25.002 .All devices being of same type, e.g.,
assemblies of rectifier diodes (EPO)
257/E25.003 ..Devices not having separate containers (EPO)

257/E25.01 ...Device consisting of plurality of
semiconductor or other solid state devices or components
formed in or on common substrate, e.g., integrated circuit
device (EPO)

257/E25.012Devices being arranged next to each other
(EPO)

6 361/705 (4 OR, 2 XR)

Class 361 : ELECTRICITY: ELECTRICAL SYSTEMS AND DEVICES

361/600 HOUSING OR MOUNTING ASSEMBLIES WITH DIVERSE
ELECTRICAL COMPONENTS

361/679 .For electronic systems and devices
361/688 ..With cooling means
361/704 ...Thermal conduction
361/705By specific coating

5 29/832 (0 OR, 5 XR)

Class 029 : METAL WORKING

29/592 METHOD OF MECHANICAL MANUFACTURE

29/592.1 .Electrical device making
29/825 ..Conductor or circuit manufacturing
29/829 ...On flat or curved insulated base, e.g.,
printed circuit, etc.

29/832Assembling to base an electrical component,
e.g., capacitor, etc.

5 165/185 (0 OR, 5 XR)

Class 165 : HEAT EXCHANGE

165/185 HEAT TRANSMITTER

5 165/80.2 (0 OR, 5 XR)

Class 165 : HEAT EXCHANGE

165/80.1 WITH RETAINER FOR REMOVABLE ARTICLE
165/80.2 .Electrical component

5 174/16.3 (0 OR, 5 XR)

Class 174 : ELECTRICITY: CONDUCTORS AND INSULATORS

174/8 WITH FLUIDS OR VACUUM

174/15.1 .With cooling or fluid feeding, circulating or
distributing

174/16.1 ..By ventilation or gas circulation

174/16.3 ...With heat sink

5 257/697 (1 OR, 4 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/688 ..With large area flexible electrodes in press
 contact with opposite sides of active semiconductor chip
 and surrounded by an insulating element, e.g., ring

257/690 ..With contact or lead

257/692 ..With particular lead geometry

257/693 ...External connection to housing

257/697 Pin grid type

5 257/778 (0 OR, 5 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD

257/778 ..Flip chip

5 257/E23.102 (0 OR, 5 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E23.079 ..For integrated circuit devices, e.g., power
 bus, number of leads (EPO)

257/E23.08 ..Arrangements for cooling, heating, ventilating
 or temperature compensation; temperature-sensing
 arrangements (EPO)

257/E23.101 ..Selection of materials, or shaping, to
 facilitate cooling or heating, e.g., heat sinks (EPO)

257/E23.102 ...Cooling facilitated by shape of device (EPO)

5 257/E23.104 (0 OR, 5 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E23.079 ..For integrated circuit devices, e.g., power
 bus, number of leads (EPO)

257/E23.08 ..Arrangements for cooling, heating, ventilating
 or temperature compensation; temperature-sensing
 arrangements (EPO)

257/E23.101 ..Selection of materials, or shaping, to
 facilitate cooling or heating, e.g., heat sinks (EPO)

257/E23.102 ...Cooling facilitated by shape of device (EPO)

257/E23.104 Characterized by shape of housing (EPO)

5 257/E23.181 (0 OR, 5 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E23.176 ...For flat cards, e.g., credit cards (EPO)

257/E23.18 ..Containers; seals (EPO)

257/E23.181 ..Characterized by shape of container or parts,
 e.g., caps, walls (EPO)

PLUS Search Results for S/N 10/600,799, Searched November 05, 2004 (Top 50)

The Patent Linguistics Utility System (PLUS) is a USPTO automated search system for U.S. Patents from 1971 to the present. PLUS is a query-by-example search system which produces a list of patents that are most closely related linguistically to the application searched. This search was prepared by the staff of the Scientific and Technical Information Center, SIRA.

4796156	6100113	5819402	5528456	5789810
4908736	5950073	6156165	5552635	5866942
4914812	6054008	4323914	5561322	5891755
6054759	4442450	5241452	5661089	5907474
4245273	5604978	5249101	5701033	5926371
4296456	5623394	5297006	5723904	5931222
4974769	5706171	5359768	5726079	5982038
4996589	5724729	5390082	5747877	5981310
5506448	5742477	5426319	5751062	6057601
5895233	5757620	5475236	5751063	6075289